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LEAD FRAME HAVING SEMICONDUCTOR DEVICE MOUNTED THEREON AND METHOD FOR FABRICATING THE SAME

Upper and lower protective protruded portions (3, 4) are formed on upper and lower surfaces of the lead frame to prevent breakage of resin mold or bending of terminals of semiconductor devices (2) mounted on a lead frame (1) during transportation of the lead frame (1) between fabrication steps thereof. The regions of the upper and lower protective protruded portions (3, 4) are located between adjacent ones of the semiconductor devices (2). Those protruded portions (3, 4) are formed simultaneously with the resin sealing of the semiconductor devices (2) by using the same resin material.

FIG. 3